



**AO8801**

**Dual P-Channel Enhancement Mode Field Effect Transistor**

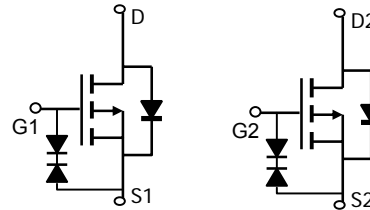
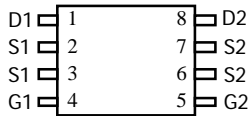
**General Description**

The AO8801 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected. *Standard Product AO8801 is Pb-free (meets ROHS & Sony 259 specifications). AO8801L is a Green Product ordering option. AO8801 and AO8801L are electrically identical.*

**Features**

- $V_{DS}$  (V) = -20V
- $I_D$  = -4.7 A ( $V_{GS}$  = -4.5V)
- $R_{DS(ON)} < 42m\Omega$  ( $V_{GS}$  = -4.5V)
- $R_{DS(ON)} < 53m\Omega$  ( $V_{GS}$  = -2.5V)
- $R_{DS(ON)} < 70m\Omega$  ( $V_{GS}$  = -1.8V)
- ESD Rating: 3000V HBM

**TSSOP-8  
Top View**



**Absolute Maximum Ratings  $T_A=25^\circ\text{C}$  unless otherwise noted**

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current <sup>A</sup>	$T_A=25^\circ\text{C}$	-4.7	A
		$T_A=70^\circ\text{C}$	
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	-30	
Power Dissipation <sup>A</sup>	$T_A=25^\circ\text{C}$	1.4	W
		$T_A=70^\circ\text{C}$	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Units	
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	$t \leq 10\text{s}$	73	90	$^\circ\text{C/W}$
		Steady-State	96	125	$^\circ\text{C/W}$
Maximum Junction-to-Lead <sup>C</sup>	$R_{\theta JL}$	63	75	$^\circ\text{C/W}$	

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$ , $V_{GS}=0\text{V}$	-20			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-16\text{V}$ , $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	$\mu\text{A}$
$I_{GSS}$	Gate-Body leakage current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 4.5\text{V}$			$\pm 1$	$\mu\text{A}$
		$V_{DS}=0\text{V}$ , $V_{GS}=\pm 8\text{V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=-250\mu\text{A}$	-0.3	-0.55	-1	
$I_{D(ON)}$	On state drain current	$V_{GS}=-4.5\text{V}$ , $V_{DS}=-5\text{V}$	-25			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5\text{V}$ , $I_D=-4.7\text{A}$ $T_J=125^\circ\text{C}$		35 47	42 57	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$ , $I_D=-4\text{A}$		44	53	$\text{m}\Omega$
		$V_{GS}=-1.8\text{V}$ , $I_D=-2\text{A}$		54	70	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS}=-5\text{V}$ , $I_D=-4.7\text{A}$	8	16		S
$V_{SD}$	Diode Forward Voltage	$I_S=-1\text{A}$ , $V_{GS}=0\text{V}$		-0.78	-1	V
$I_S$	Maximum Body-Diode Continuous Current				-2.2	A
<b>DYNAMIC PARAMETERS</b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}$ , $V_{DS}=-10\text{V}$ , $f=1\text{MHz}$		1450		pF
$C_{oss}$	Output Capacitance			205		pF
$C_{rss}$	Reverse Transfer Capacitance			160		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $f=1\text{MHz}$		6.5		$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g$	Total Gate Charge	$V_{GS}=-4.5\text{V}$ , $V_{DS}=-10\text{V}$ , $I_D=-4\text{A}$		17.2		nC
$Q_{gs}$	Gate Source Charge			1.3		nC
$Q_{gd}$	Gate Drain Charge			4.5		nC
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=-4.5\text{V}$ , $V_{DS}=-10\text{V}$ , $R_L=2.5\Omega$ , $R_{GEN}=3\Omega$		9.5		ns
$t_r$	Turn-On Rise Time			17		ns
$t_{D(off)}$	Turn-Off Delay Time			94		ns
$t_f$	Turn-Off Fall Time			35		ns
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=-4\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$		31		ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=-4\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$		13.8		nC

A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any a given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 $\mu\text{s}$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The SOA curve provides a single pulse rating. Rev2: August 2005

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

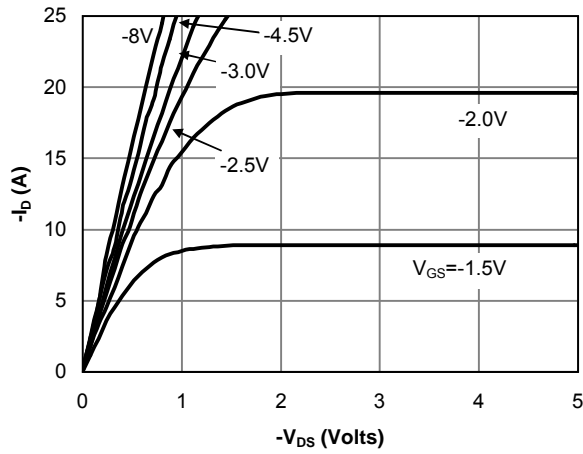


Fig 1: On-Region Characteristics

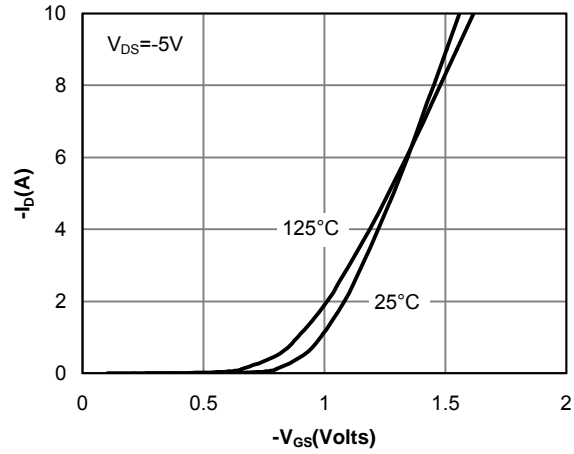


Figure 2: Transfer Characteristics

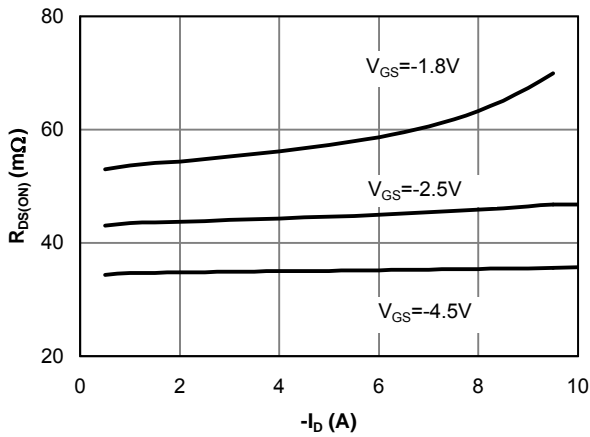


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

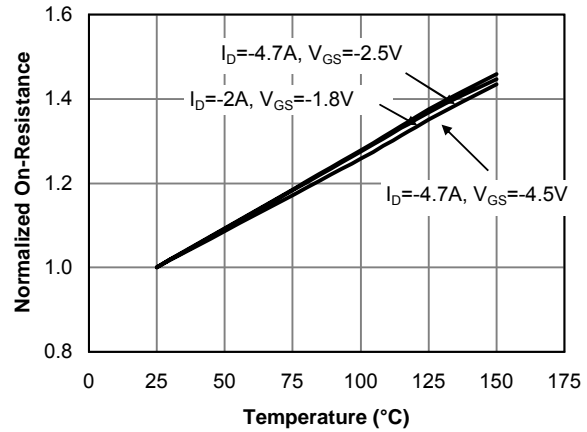


Figure 4: On-Resistance vs. Junction Temperature

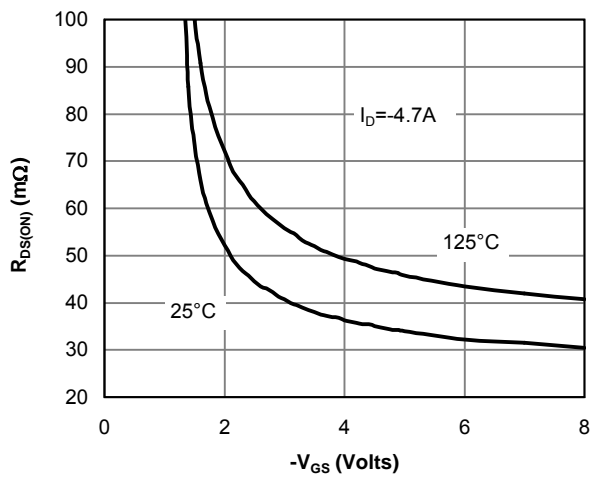


Figure 5: On-Resistance vs. Gate-Source Voltage

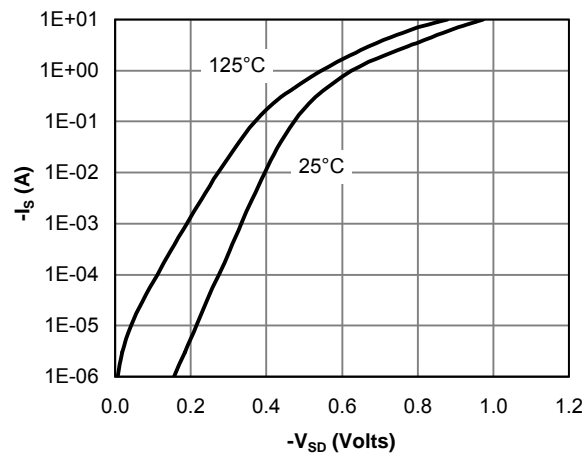


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

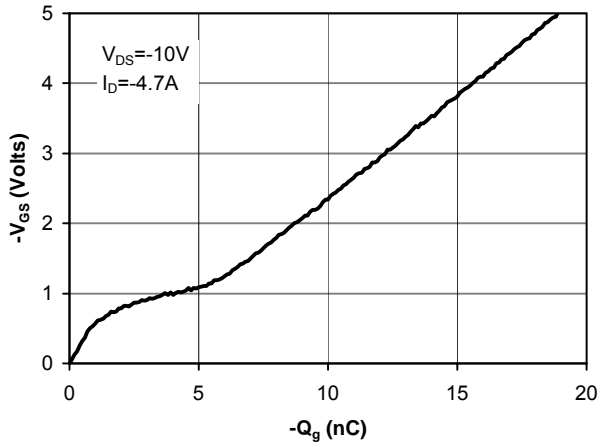


Figure 7: Gate-Charge Characteristics

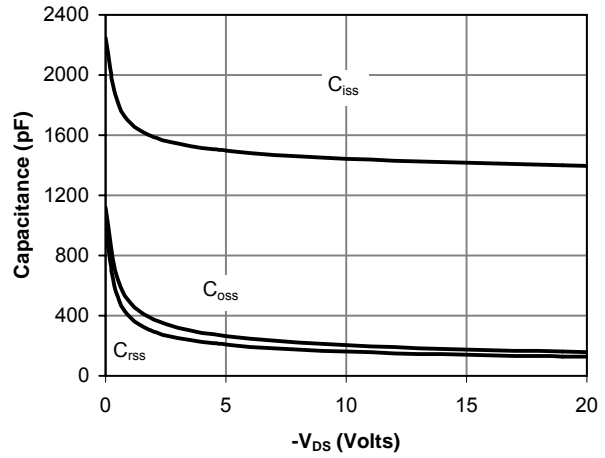


Figure 8: Capacitance Characteristics

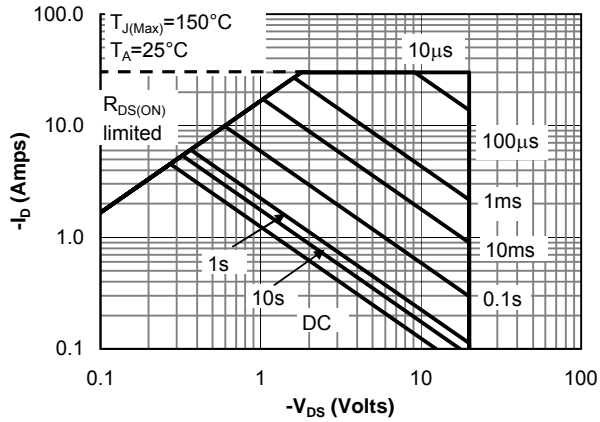


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

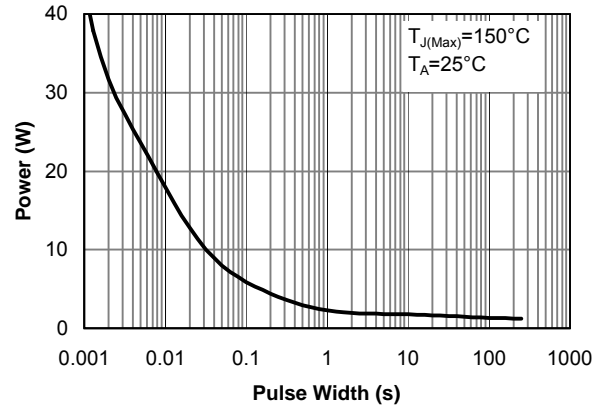


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

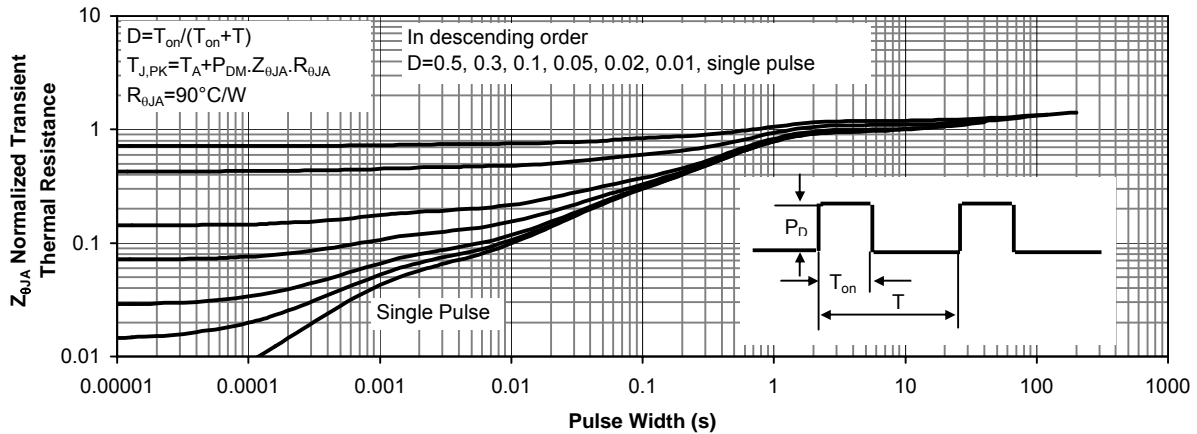
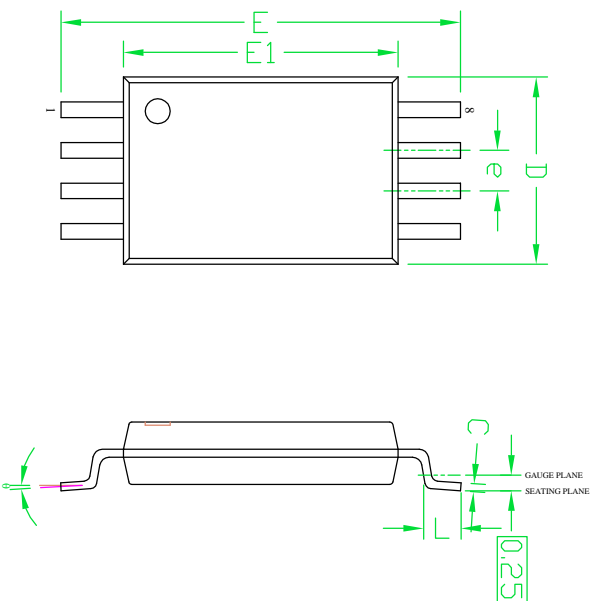
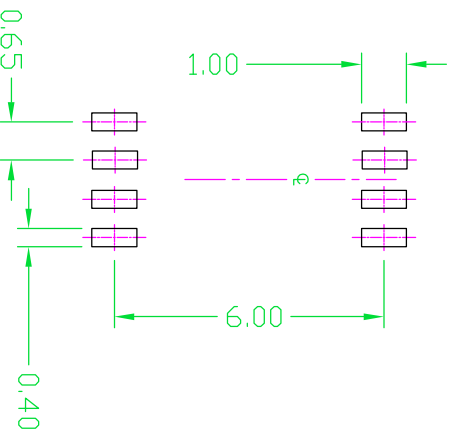


Figure 11: Normalized Maximum Transient Thermal Impedance



- NOTE**
1. ALL DIMENSIONS ARE IN MILLIMETERS.
  2. DIMENSIONS ARE INCLUSIVE OF PLATING
  3. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
  4. DIMENSION L IS MEASURED IN GAUGE PLANE.
  5. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
  6. FOLLOWED FORM JEDEC MO-153(AA)

**RECOMMENDED LAND PATTERN**



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.05	1.00	1.20	0.002	0.039	0.047
A1	0.05	1.00	1.15	0.002	0.039	0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19	---	0.30	0.007	---	0.012
C	0.09	---	0.20	0.004	---	0.008
D	2.90	3.00	3.10	0.114	0.118	0.122
E	---	6.40 BSC	---	---	0.252 BSC	---
E1	4.30	4.40	4.50	0.169	0.173	0.177
e	---	0.65 BSC	---	---	0.026 BSC	---
L	0.45	0.60	0.75	0.018	0.024	0.030
θ	0°	---	8°	0°	---	8°

UNIT: mm

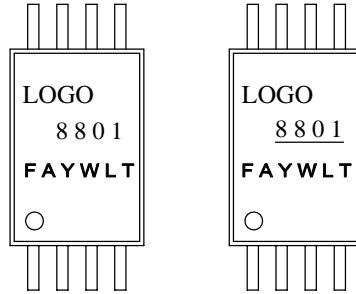
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES DECIMAL X.X ± XXX ± XXXX ± INTERPRET DIM AND TOL PER ASME Y14.5M - 1994	THIRD ANGLE PROJECTION 	Document No.	
		Version	
PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING	Title	TSSOP-8 PACKAGE OUTLINE	



**ALPHA & OMEGA**  
SEMICONDUCTOR, LTD.

Document No.	PD-00117
Version	rev B
Title	AO8801 Marking Description

TSOP-8 PACKAGE MARKING DESCRIPTION



Standard product

Green product

NOTE:

- LOGO - AOS LOGO
- 8801 - PART NUMBER CODE.
- F&A - FOUNDRY AND ASSEMBLY LOCATION
- Y - YEAR CODE
- W - WEEK CODE.
- L T - ASSEMBLY LOT CODE

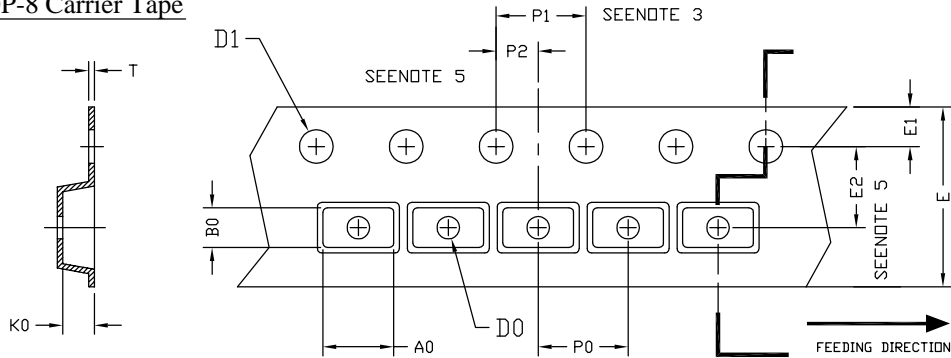
PART NO.	DESCRIPTION	CODE
AO8801	Standard product	8801
AO8801L	Green product	<u>8801</u>



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## TSSOP-8 Tape and Reel Data

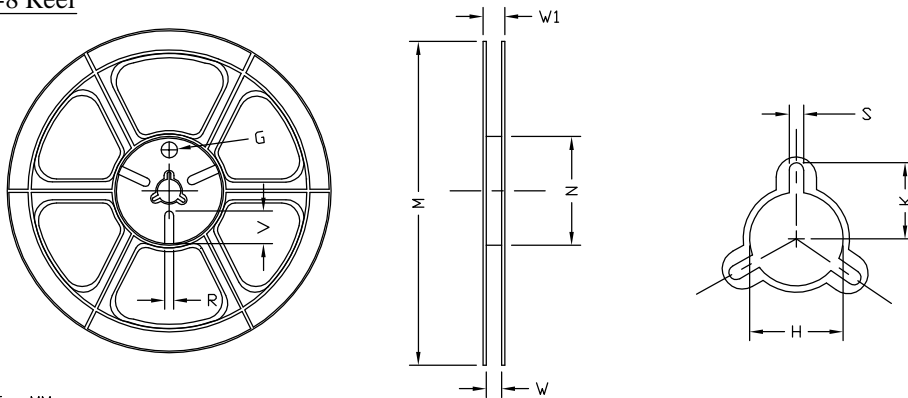
### TSSOP-8 Carrier Tape



UNIT: MM

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SD-8 (12 mm)	6.80 ±0.10	3.40 ±0.10	1.60 ±0.10	1.50 ±0.10	1.50 MIN.	12.00 ±0.30	1.75 ±0.10	5.50 ±0.05	8.00 ±0.10	4.00 ±0.10	2.00 ±0.10	0.30 ±0.05

### TSSOP-8 Reel



UNIT: MM

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
12 mm	φ330	φ178.00 ±0.50	φ60.00 ±0.50	13.00 +1.50 -0.00	16.00 ±1.00	φ13.50 ±0.50	10.60	2.20 ±0.50	---	---	---

### TSSOP-8 Tape

Leader / Trailer  
& Orientation

